

FROM : Microchip T2

FAX NO. : 408 792 3980

Nov. 21 2003 06:05PM P2

PATENTIN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	:	09/990,991	Confirmation No.	4299
Att'y	:	Daniel C. Baker		
Filed	:	November 16, 2001		
TC/A.U.	:	1734		
Examiner	:	George R. Koch		
Docket No.	:	PIIA 51232A (VLSI.273DIV1)		
Customer No.	:	24738		
Title:	Photoresist Dispense Arrangement by Compensation for Substrate Reflectivity			

Declaration Under 37 C.F.R. §1.131

I, Daniel C. Baker, hereby present the following declarations.

Before October 6, 1999, while employed by VLSI Technology, Inc., now Philips Electronics North America):

1. I invented an arrangement and method for applying photosensitive material to a semiconductor wafer. The invention has been found to particularly suited for forming photo resist layers on substrates that have consistent thickness and uniformity across the wafer from lot to lot.

2. I prepared the Invention Disclosure for the above-named invention. This invention disclosure statement was submitted to the Legal Department before October 6, 1999, and subsequently used in the preparation of the above-referenced patent application.

3. As sole inventor, I prepared and signed or initialed an eight (8)-page invention disclosure statement, a true and accurate copy of which is attached hereto as an Exhibit, with pertinent dates intentionally blocked out (each date preceding October 6, 1999). This invention disclosure statement provides details of the above-named invention.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Signed this 21 day of November 2003 by:

Daniel C. Baker  
Daniel C. Baker

FROM : Microchip T2

FAX NO. : 480 792 3980

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**INVENTION DISCLOSURE FORM**  
COMPANY Confidential and Proprietary

Invention Disclosure No:

3	4	4	5
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PRINT DATE 12/19/03  
EXHIBIT

This is a Disclosure Form for VLSI Technology, Inc. all of its related companies hereafter referred to as "COMPANY"

## Instructions:

- Use this form only if electronic versions are not accessible or available.
- Please write legibly in ink.
- Complete all sections. Attach supplemental pages and other documentation as required.

Date Stamp:

**Date Redacted**

Return Completed Form To:

1109 McKay Drive  
San Jose, California 95131

## 1. Title of the Invention

Write a short descriptive title, avoiding coined names and project names.

## 2. Inventors

Include names of all persons who made a contribution to the conception and/or reduction to practice of the invention.  
If there are more than five inventors, use a Supplemental Sheet.

Full Name 1: Daniel C. Baker

Home Address: 470 Dixon Landing Road, Glou  
Milpitas, CA 95035  
Home Phone: 408-458-8771

Mail Stop #2

Location: Suite 300

Work Phone: 408-434-3102

E-Mail: dan.baker@vlsi.com

Department: Technology Development

APC Group:

Supervisor: Satyendra Sethi

Employee No.: 2466

Full Name 2:

Mail Stop

Home Address:

Location

Home Phone:

Work Phone:

Citizenship:

E-Mail:

Supervisor:

Department:

Employee No.:

APC Group:

Full Name 3:

Mail Stop

Home Address:

V

Home Phone:

Work Phone:

Citizenship:

E-Mail:

Supervisor:

Department:

Employee No.:

APC Group:

Full Name 4:

Mail Stop

Home Address:

Location

Home Phone:

Work Phone:

Citizenship:

VAX Name:

Supervisor:

Department:

Employee No.:

APC Group:

Full Name 5:

Mail Stop

Home Address:

Location

Home Phone:

Work Phone:

Citizenship:

VAX Name:

Supervisor:

Department:

Employee No.:

APC Group:

Inventors' Initials: DCBPage 1 of 8Witnesses' Initials: IY L.Z.

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## INVENTION DISCLOSURE FORM

Invention Disclosure No:    **3. Brief Description of the Invention (Invention Summary).** This field must be filled in or disclosure is not complete.

Describe the structure, function and/or method of the invention. Stress the fundamental principle of the new idea from an engineering standpoint. Present the idea in a nutshell. This description will be entered into the VLSI Patent Database so that your colleagues can be informed of your invention. Description should be 25 to 50 words in length.

Altered photoresist dispense methods vary wafer rotation speed during chemical delivery in order to achieve uniform coatings with minimal volume (less waste). In order for these techniques to work there must be hardware used to detect the precise instant that photoresist comes in contact with the wafer. Variations in substrate reflectivity cause variations in the detection of this event, leading to photoresist thickness and uniformity. This invention describes a hardware modification to allow compensation for wafer reflectivity which will lead to consistent coating on all substrates.

**4. Detailed Description of Invention**

Describe the structure, function and/or method of the invention in detail. Here, go in sufficient detail for someone to understand and be able to practice your invention. At a minimum, this would be from 1 to 2 pages. Use as many pages as required to get your idea across. Use Supplemental Sheets (Section 18) as needed.

**5. Conception of the Invention**

Date of conception: Date Redacted

Location of conception: San Jose

Date of first written description: Date Redacted

Lab notebook no: 250

Page(s): 12-13

Please attach copies of all pertinent lab notebooks or equivalent. They should be signed, dated and witnessed by one or more people who have read and understood the description of the invention.

**6. Reduction to Practice**

Reduction to practice is demonstrating that an invention merely works with evidence such as working models, prototypes or simulations. Reduction to practice is not necessary to file a patent application.

Date of any such demonstration:

Location of demonstration:

**7. Project/Release/Sale Information**

A sale, offer for sale, public showing or release of the invention may affect COMPANY's right to patent the invention. Submit this form even if a public

Inventors' initials ADWitnesses' initials JB LZPage 2 of 8

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**INVENTION DISCLOSURE FORM**  
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Invention Disclosure No:

<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
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sale, showing or release has occurred.

Field of technology (e.g., encryption, microprocessor, audio)

Project name and description:

Product name and model number:

Please list docket numbers of all other invention disclosures that are related to this one:

Estimated/actual date of first public release or showing of invention or product incorporating or using the invention: None

Estimated/actual manufacturing release date of invention or product incorporating or using the invention:

Estimated/actual date of offer for sale of product incorporating or using the invention:

**8. Publication of the Invention**

Publication of a description of the invention may affect COMPANY's right to patent the invention. Submit this form even if publication has occurred.

Has a description been published or is it scheduled to be published? **No**

If "Yes," when and to whom:

Has a description been disclosed or is it schedule to be disclosed? **No**

If "Yes," when and to whom?

Was a Non-Disclosure Agreement used **No**

If "Yes," please attach copy

**9. Government Agency Contract**Was this invention made under a government agency contract? **No**

If "Yes," government agency contract number:

**10. Joint Development or Development Contract**Inventors' Initials BBPage **3** of **8**Witnesses' Initials TB LZ

Date Redacted



**INVENTION DISCLOSURE FORM**  
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Invention Disclosure No:

Was this invention jointly developed with inventors from another company? **No**

If "Yes," please identify the company and/or non-COMPANY inventors:

Was the invention tested, constructed or conceived pursuant to the performance of a development contract with another company? **No**

If "Yes," please identify the contract and its location

**11. Related Art**

Is this invention an improvement of an existing COMPANY product? **No**

If "Yes," identify the existing product:

Closest known related art:

What was the problem to be solved?

How had others attempted to solve it before you?

What were the problems or disadvantages with prior solutions?

**12. Reference Materials**

List any printed publications, patents, patent applications or any other materials you are aware of which provides background material and/or prior art for your invention.

Date of Publication

Author

Title

Use Supplemental sheet(s) for additional Reference Materials exceeding five Entries.

Inventor's Initials DWD \_\_\_\_\_

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Witnesses' Initials TB L.Z.

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**INVENTION DISCLOSURE FORM**  
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Invention Disclosure No:

**13. Licensing/Competitive Analysis**

Is this a licensable technology? Yes

If "Yes," name the fields in which this might be licensed: Semiconductor Manufacturing, Device Manufacturers

If "Yes," name the companies which may possibly be interested: Dia nippon Screen, SVG, TEL

**14. Drawings of the Invention**

Please submit clear drawings which illustrate the invention using the supplemental sheets.

**15. Attorney/Agent**If there is a particular patent attorney or agent with whom you would  
like to work on this disclosure, suggest his/her name.

Inventors' Initials

JMBPage 5 of 8

Witnesses' Initials

TJ L.E.

Date Redacted



**I INVENTION DISCLOSURE FORM  
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Invention Disclosure No:

**16. Signatures of Inventors**

This Invention Disclosure Form is submitted pursuant to your employment agreement with COMPANY. Use a Supplemental Sheet if there are more than 5 inventors. Please sign and date below and be certain that each page of this disclosure has been initialed by each inventor.

Signature:

Date:

Date Redacted

Full Name of Inventor 1

Signature:

Date:

Full Name of Inventor 2

Signature:

Date:

Full Name of Inventor 3

Signature:

Date:

Full Name of Inventor 4

Signature:

Date:

Full Name of Inventor 5

**17. Read and Understand**

This Invention Disclosure Form consisting of 7 pages has been read and understood by:

Signature:

Name:

TAMMY ZHENG

Name of Witness 1

Date:

Date Redacted

Signature:

Name:

Li Ming Zhang

Name of Witness 2

Date:

Date Redacted

Witnesses, please initial all supplemental pages.

Inventors' Initials

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Witnesses' Initials

Date Redacted



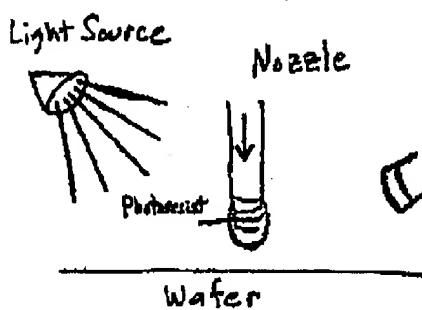
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Invention Disclosure No.

**18. Supplemental Sheet(s)**

Add necessary description supported by relevant documentation. Such documentation may include experimental results, xeroxed copies of pages of Lab Notebooks and the like, electronic files, plots. Be as thorough as possible in your disclosure. A thorough disclosure greatly assists the attorney or agent in preparing a patent application.

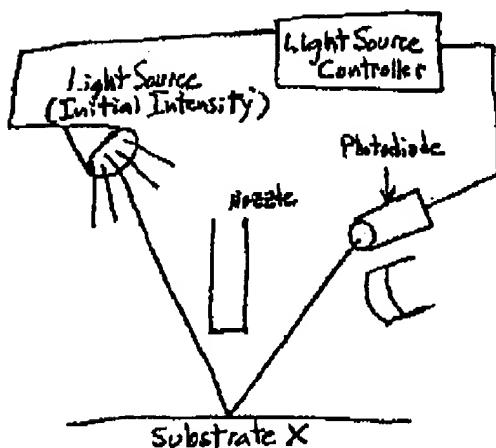
Primary Invention:



Current System

Variation when substrate is dark (more resist dispensed) to overly sensitive on bright substrate (less dispense). Signal may also be too dim or washed out, causing mechanism to fail.

\* Modified System: Photodiode detector is added to check reflectivity of each wafer prior to photoresist dispense. Illumination of light source is adjusted automatically to optimum level. Photoresist is dispensed

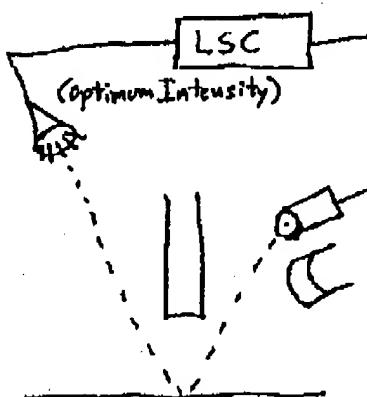


STEP - 1

Reflectivity Measured

Inventors' Initials

BB

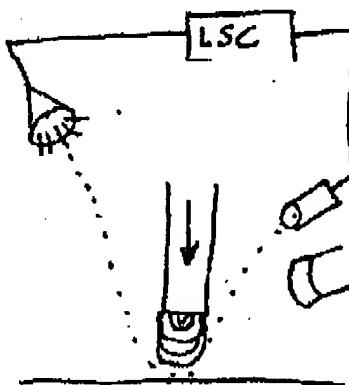


STEP - 2

Reflectivity Adjusted to  
Predetermined optimum

Witnesses' Initials

78 L.Z.



STEP - 3

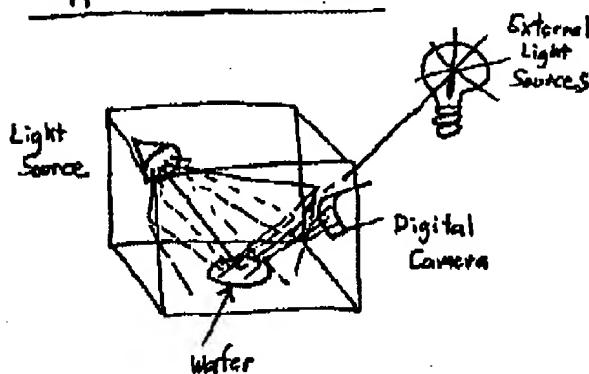
Photoresist Dispense

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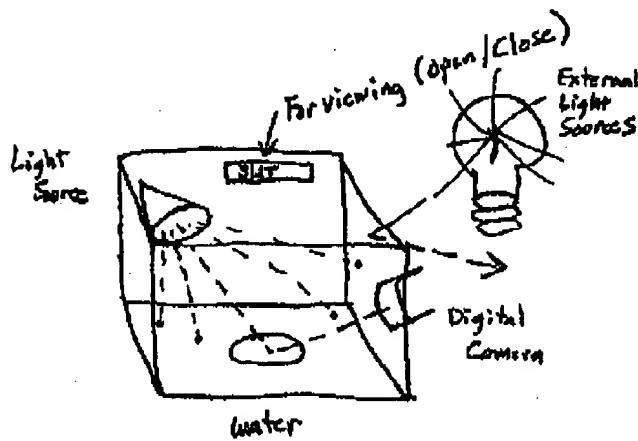
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COMPANY Confidential and ProprietaryInvention Disclosure No:    

## 18. Supplemental Sheet(s)

Add necessary description supported by relevant documentation. Such documentation may include experimental results, xeroxed copies of pages of Lab Notebooks and the like, electronic files, plots. Be as thorough as possible in your disclosure. A thorough disclosure greatly assists the attorney or agent in preparing a patent application.

Supplemental Invention:Current System

Coat module is enclosed area with both reflective surfaces and transparent windows. This allows stray light from internal and external sources to affect the detection system.

Modified System

Reduce transparent window area (slits) and coat all surfaces with non-reflective material. Signal noise is reduced and substrate reflectivity measurement will be consistent.

Inventors' Initials ABWitnesses' Initials Tx LZPage 2 of 2